

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	US "20020112964" A1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	OFF	2005/08/19 16:17
S2	4	low adj acid and within adj die	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	OFF	2005/08/19 16:20
S3	6	low adj acid and leveller	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	OFF	2005/08/19 16:32
S4	49	low adj acid and leveler	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	OFF	2005/08/19 18:00
S5	38	leveler with copper with concentration	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	OFF	2005/08/19 18:01

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	142	suppressor electroplating wafer defect	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2005/08/15 14:26
S2	5	suppressor electroplating wafer defect	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	SAME	ON	2005/08/15 14:45
S3	4	suppressor chloride cataly\$3 defect	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	SAME	ON	2005/08/15 14:47
S4	5	suppressor (chloride same cataly\$3) defect electroplating wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2005/08/15 14:50
S5	62	(suppressor same chloride) defect electroplating wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2005/08/15 15:23
S6	9	(suppressor same chloride) defect electroplating wafer (high adj acid)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2005/08/15 14:51
S7	11	(suppressor same chloride) (defect with pit\$4) electroplating	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2005/08/18 09:54
S8	3	(chloride with concentration) same ("feature size" or "aspect ratio") electroplating	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	OFF	2005/08/18 09:55
S9	66	(chloride with concentration) same ("feature size" or "aspect ratio")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	OFF	2005/08/18 09:52
S10	7164	chloride same copper same (electroplating or plating or deposition or electrodeposition)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2005/08/18 09:55

S11	29	(chloride with concentration) same ("feature size" or "aspect ratio") and (electroplating or plating or deposition or electrodeposition)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	OFF	2005/08/18 09:56
S12	685	concentration with ("aspect ratio" or "feature size")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	OFF	2005/08/19 14:30
S13	65	concentration with ("aspect ratio" or "feature size") same ("electroplating" or "plating" or electrodeposition or deposition)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	OFF	2005/08/19 14:33